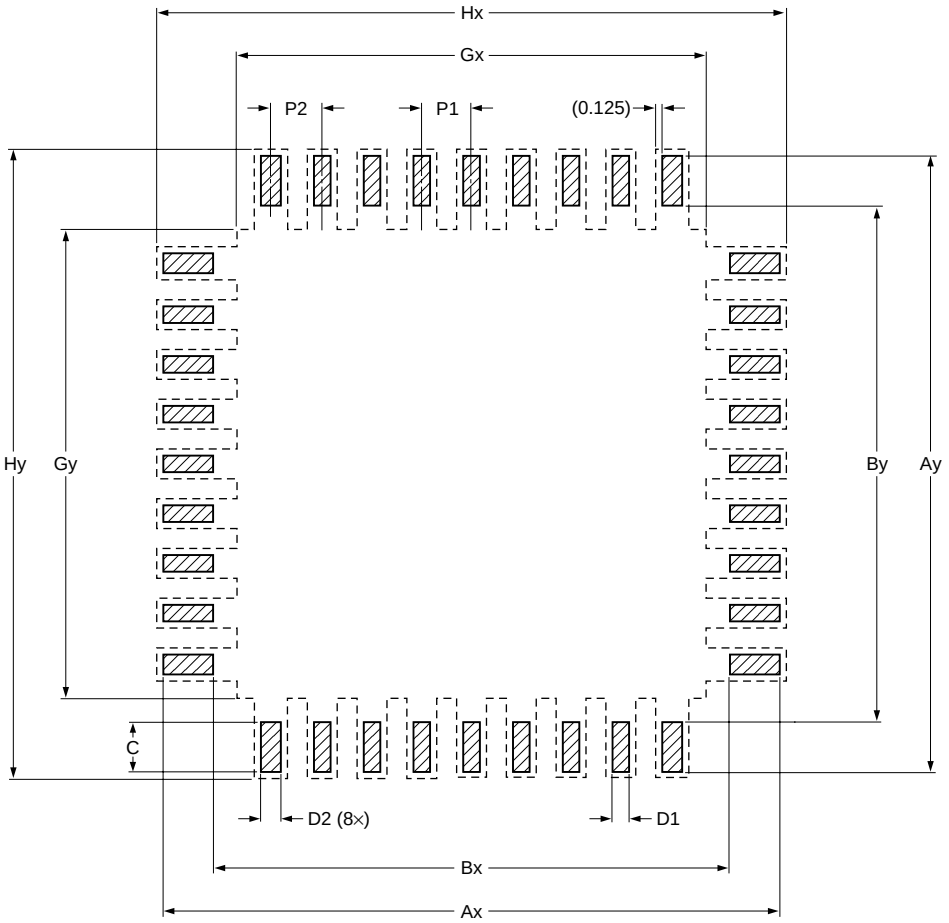
Footprint information for reflow soldering of QFP100 package **SOT317-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.700	25.300	19.300	20.900	14.900	2.200	0.400	0.500	20.500	14.500	25.550	19.550

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